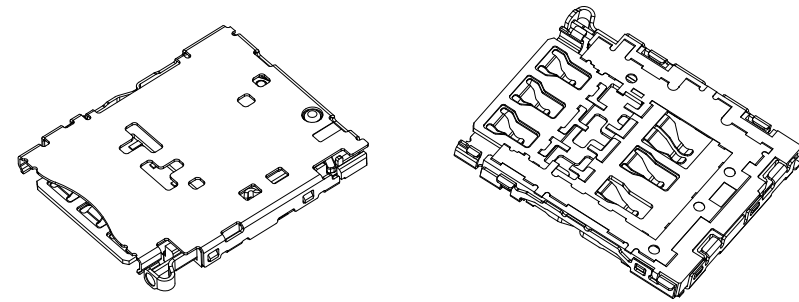
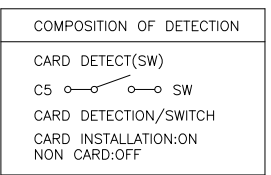


RECOMMEND P.C.B LAYOUT  
(General tolerance ±0.05)



NOTE:

- Material:
  - Housing: High Temperature Thermoplastic, (LCP S475) Color Black UL 94V-0
  - Contact: Phosphor Bronze (C5210R-H, T=0.08±0.01mm)
  - Cover: SUS301-H T=0.15±0.03mm
- Plating:
  - Contact terminal:  
Contact area: Gold 1u" Min.  
Solder area: Gold 0.8u" Min.  
Underplating: Ni overall 50u" Min.
  - Cover:  
Underplating: Ni overall 30u" Min.  
Solder area: Gold 0.8u" Min.
- Specification:
  - Current Rating :0.5mA max.
  - Contact Resistance: 50 mOhms max
  - Insulation Resistance: 1000 MOhms min./500VDC
  - Dielectric Withstanding Voltage: 500 V AC/1minute
  - Operating Temperature: -25°C to +85°C
  - Mating Cycles: 5000 Insertions

SIM Card Pin Assignments

NANO SIM CARD	
C1	Vcc
C2	RST
C3	CLK
C5	GND
SW	CD/SW
C6	Vpp
C7	DATA

	深圳市鑫南天科技有限公司 Shenzhen XinNanTian Technology Co., Ltd				
	DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE DIMENSION TOLERANCE X.X: ± 0.38 X.XX: ± 0.25 X.XXX: ± 0.10 ANGULAR: ± 1°	PRODUCT NAME : nano sim 1.5H connector PRODUCT NO. : XNT-SMN150-T1131-11 DRAWING NO. : XNT-SMN150-T1131-11	DRAWING: COCO CHECK: AG APPROVED: JEFF	DATE: 2016/12/12 DATE: 2016/12/12 DATE: 2016/12/12	
		SCALE: NA	DWG ID: P D	REV.: A	PAGE: 1 OF 1

REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
1				
2				
3				